

Description

The AOSS21319C uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 2.5V.

This device is suitable for use as a Battery protection or in other Switching application.

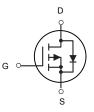


General Features

 V_{DS} = -30V, I_D = -4.1A $R_{DS(ON)}$ <55m Ω @ V_{GS} =10V

Application

High power and current handing capability
Lead free product is acquired
Surface mount package
PWM applications
Load switch
Power management



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
AOSS21319C	SOT-23-3L	HXY MOSFET	3000

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage	-30	V
V _G S	Gate-Source Voltage	±20	V
ID	Drain Current-Continuous	-4.1	А
Ірм	Drain Current-Pulsed (Note 1)	-13	А
P _D	Maximum Power Dissipation	1.32	W
T _J ,T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$ C
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	125	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
△BV _{DSS} /△T _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.02		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V_{GS} =-10 V , I_D =-3 A		42	55	mΩ
		V _{GS} =-4.5V , I _D =-1.5A		90	98	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.5	-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS=VDS , ID =-250UA		4.32		mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	- uA
		V _{DS} =-24V , V _{GS} =0V , T _J =55°C			-5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA
gfs	Forward Transconductance	V_{DS} =-5 V , I_{D} =-3 A		4.8		S
R_g	Gate Resistance	V_{DS} =0 V , V_{GS} =0 V , f=1 MHz		24	48	Ω
Qg	Total Gate Charge (-4.5V)	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-3A		5.22	7.3	nC
Q_{gs}	Gate-Source Charge			1.25	1.8	
Q_{gd}	Gate-Drain Charge			2.3	3.2	
T _{d(on)}	Turn-On Delay Time			18.4	37	
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω		11.4	21	200
T _{d(off)}	Turn-Off Delay Time	I _D =-1A 39.4		79	ns	
Tf	Fall Time			5.2	10.4	1
C _{iss}	Input Capacitance			463	650	
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		82	115	pF
Crss	Reverse Transfer Capacitance			68	95	
Is	Continuous Source Current ^{1,4} Pulsed Source Current ^{2,4} V _G =V _D =0V , Force Current				-3.2	Α
I _{SM}			1		-13	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	-		-1	V

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The power dissipation is limited by 150°C junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

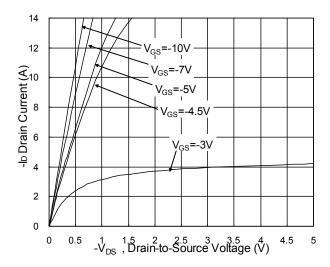


Fig.1 Typical Output Characteristics

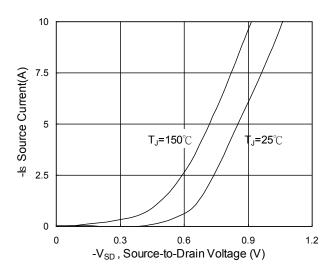


Fig.3 Source Drain Forward Characteristics

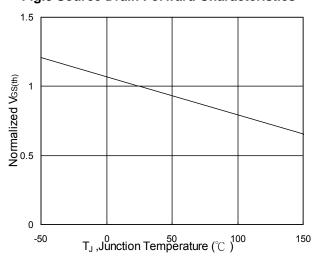


Fig.5 Normalized V_{GS(th)} vs. T_J

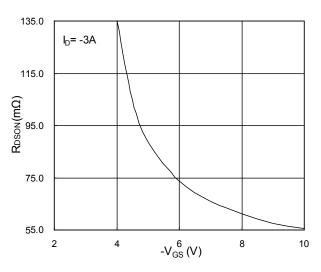


Fig.2 On-Resistance vs. G-S Voltage

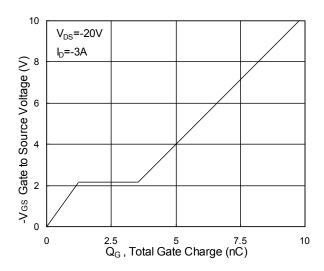


Fig.4 Gate-Charge Characteristics

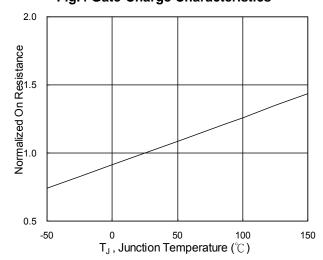
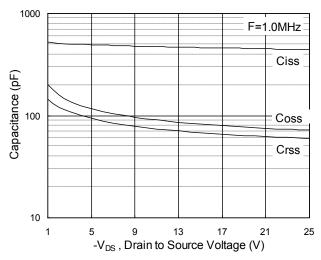


Fig.6 Normalized R_{DSON} vs. T_J





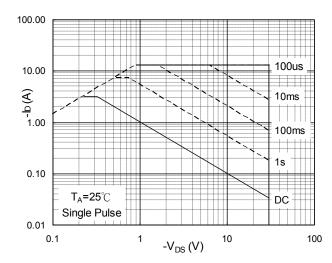


Fig.7 Capacitance

Fig.8 Safe Operating Area

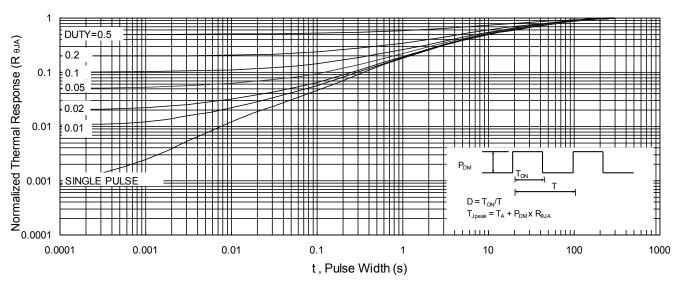
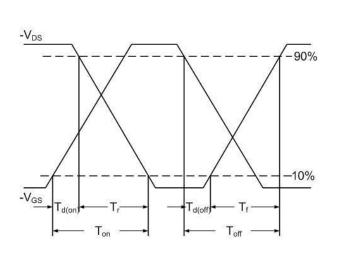


Fig.9 Normalized Maximum Transient Thermal Impedance



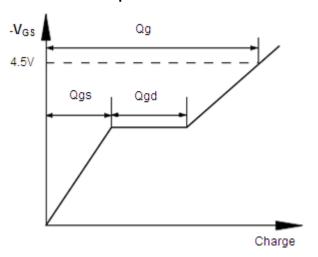
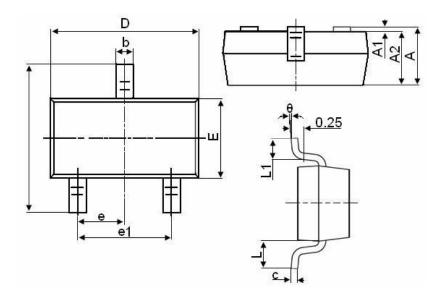


Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform



SOT-23-3LPackage Information



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
А	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.300	0.500	
С	0.100	0.200	
D	2.800	3.000	
Е	1.500	1.700	
E1	2.650	2.950	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.600	
θ	0°	8°	



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